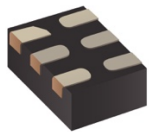


# MATERIAL DECLARATION SHEET



Material Number	CDDFN6-3312P			
Product Line	Semiconductor Products			
Compliance Date	2020/9/11			
RoHS Compliant	<b>Yes</b>	MSL	<b>3</b>	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.03000	Silicon	7440-21-3	100.00%	1.945%	1.945%
2	Lead Frame	Noble metal	0.00154	Silicon	7440-21-3	0.30%	0.100%	33.206%
			0.01536	Nickel	7440-02-0	3.00%	0.996%	
			0.00102	Magnesium	7439-95-4	0.20%	0.066%	
			0.00015	Gold	7440-57-5	0.03%	0.010%	
			0.00015	Silver	7440-66-6	0.03%	0.010%	
			0.00015	Palladium	7440-05-3	0.03%	0.010%	
			0.49368	Copper	7440-50-8	96.41%	32.014%	
3	Epoxy	Polymer	0.005224	Aluminum oxide	1344-28-1	52.24%	0.339	0.648%
			0.001492	Epoxy resin 1	Proprietary	14.92%	0.097	
			0.001492	Epoxy resin 2	Proprietary	14.92%	0.097	
			0.001492	Epoxy resin 3	Proprietary	14.92%	0.097	

# MATERIAL DECLARATION SHEET



			0.00015	Silicone Resin	Proprietary	1.50%	0.010	
			0.00015	substituted silane	Proprietary	1.50%	0.010	
4	Wire	Noble metal	0.01000	Gold	7440-57-5	99.99%	0.648%	0.648%
			0.00000	Misc, not to declare	/	0.01%	0.000%	
5	Mold Compound	Polymer	0.02940	Epoxy resin	Trade Secret	3.00%	1.907%	63.553%
			0.02940	Phenol resin	Trade Secret	3.00%	1.907%	
			0.78645	Silica (Amorphous) A	60676-86-0	80.25%	51.001%	
			0.13230	Silica (Amorphous) B	7631-86-9	13.50%	8.579%	
			0.00245	Carbon Black	1333-86-4	0.25%	0.159%	
		Total weight	<b>1.54205</b>					

This Document was updated on: 2020/9/11

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.